

TAPE Attachment Method

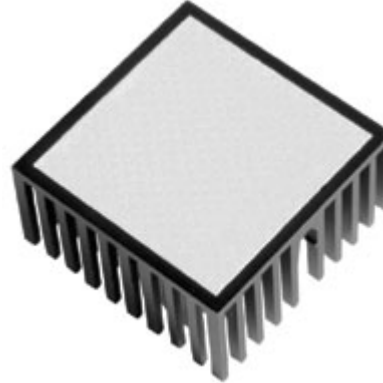
Part Number: 371824B00032G



BGA Surface	Tape Type	Heat Sink Finish
Metal	T405R	Black Anodize

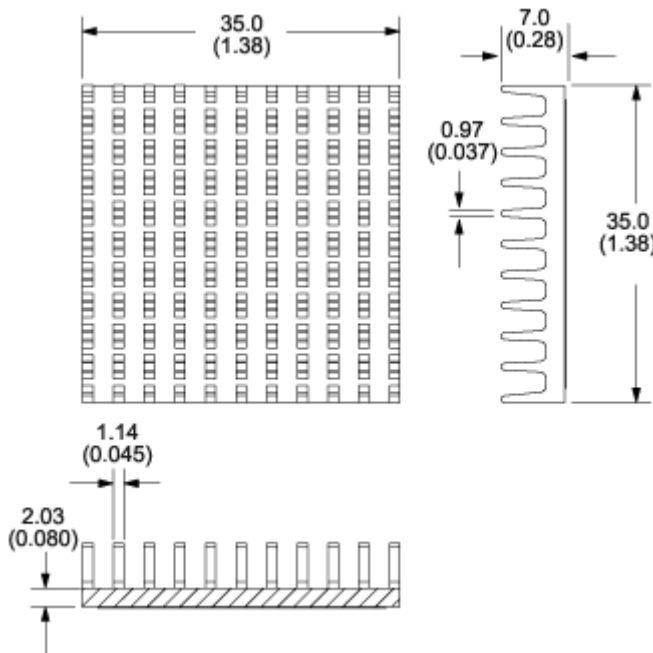
Features and Benefits

- Configurations are available for a wide range of BGA package sizes
- Tape mounted versions eliminate the need for mounting holes in the PC Board
- These Heat Sinks can be used with either plastic or metal/ceramic BGA Packages depending on tape used
- These Heat Sinks are compatible with Ther-a-grip tapes



Width	Length	Height	Fin Thickness Across Width	Fin Thickness Across Length	Base Thickness	# of fins across width	# of fins across length
35mm	35mm	7mm	0.97mm	1.14mm	2.03mm	11	11

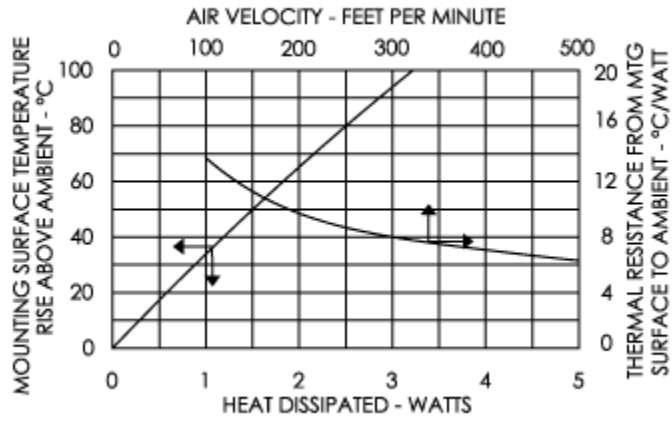
Mechanical Outline Drawing



Unless otherwise shown, tolerances are $\pm 0.38(\pm 0.015)$

Thermal Performance

* θ_n	** θ_f
31.9	9.67



*Natural convection thermal resistance is based on a 75 °C heat sink temperature rise.

**Forced convection thermal resistance based on an entering 1.0 m/s (200 lfm) airflow.
 Due to various heat dissipation paths within a BGA device, please test the heat sink in your application.

